

Solderite Flux #177, WPF-207

Introduction :

Various methods have been used for the protection of copper foil of printed circuit boards. It is predicted, however, that the use of lead contained in organic solvent of resin-based pre-flux and in solder leveler would become stricter in future from the viewpoint of dealing with environmental problems.

Under such situations, a great expectation is placed on water-soluble, heat-resistant pre-flux. A problem exists, however, that the gold-plated section is discolored if water-soluble, heat-resistant pre-flux was used for gold-plated, mixed load boards so that its use has been restricted.

Although a type of water-soluble, heat-resistant pre-flux has been developed to properly deal with the discoloration of gold plate, problems have been left unsolved, such as long processing time and discoloration of gold-plated section due to the mixing of copper ion with the processing of boards.

The processing method of water-soluble, heat-resistant pre-flux on gold-plated, mixed load boards has been firmly established this time. The processing method enables to apply water-soluble, heat-resistant pre-flux without causing any discoloration in gold-plated section.

Outstanding Features :

- Discoloration of gold-plated section will be prevented.
- Film coat can be formed in a processing time from 60 to 90 seconds.
- Thanks to the copper ion removal system, the frequency of WPF-207 liquid replacement due to the mixing of copper ion can be lessened.
- Since a thin uniform film is formed and excellent in smoothness of copper foil land, so that suitable for high-density packaged boards.
- Noninflammable. (Non-organic solvent)

Specifications :

#177 :

Appearance	: Slightly whitish liquid
Specific gravity	: 0.976 ± 0.010 (20)
PH	: 8.6 ± 0.1 (20)
Density of effective ingredients	: 100 ± 10 %

WPF-207 :

Appearance	: Colorless, transparent liquid
Specific gravity	: 1.01 ± 0.01 (20)
PH	: 3.20 ± 0.10 (20)
Acid value	: 35 ± 5
Density of effective ingredients	: 100 ± 10 %

